# Substrate-Product Substrate Combination as Well as Device and Process for Producing a Substrate-Product Substrate Combination

## Abstract

The invention relates to a process for producing a substrate-product substrate combination by aligning, bringing into contact, and bonding a contact side (2o) of a large-area substrate (2, 2') to a support surface (5o) of a carrier substrate (5, 5'), whereby the substrate (2, 2') - when contact is produced - has a larger mean diameter d1 than the mean diameter d2 of the carrier substrate (5, 5').

Moreover, the invention relates to a substrate (2, 2') for producing a substrate-product substrate combination by aligning, bringing into contact, and bonding a contact side (2o) of the large-area substrate (2, 2') to a support surface (5o) of a carrier substrate (5, 5'), whereby the substrate (2, 2') has a diameter d1, which can be reduced during back-thinning by the shape of the cross-section of the substrate (2, 2') on its peripheral contour (2u).

In addition, the invention relates to a corresponding device and a use of a large-area substrate (2) with a mean diameter d1 for aligning and bringing into contact a carrier substrate (5) with a mean diameter d2 for the further processing of the large-area substrate (2), whereby the mean diameter d1 is larger than the mean diameter d2.

Figure 3a